

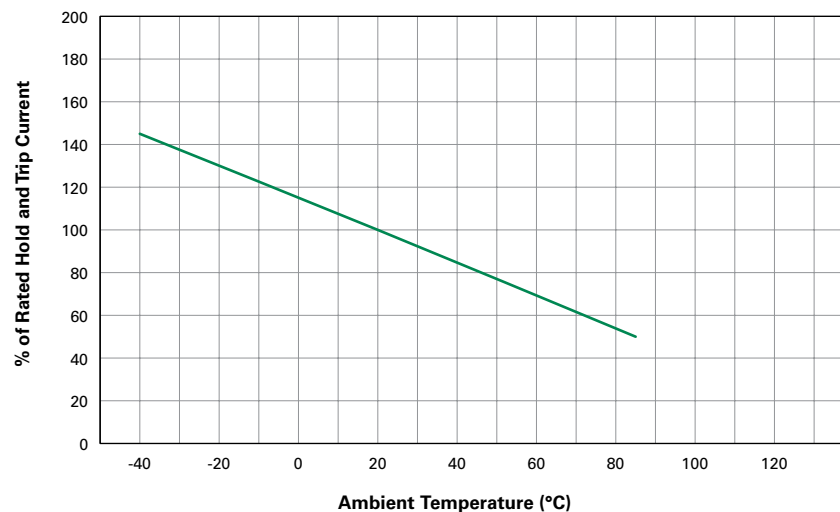
microSMD Series

Surface Mount

Temperature Derating

Maximum Ambient Temperature											
Part Number	-40°C	-20°C	0°C	20°C	25°C	40°C	50°C	60°C	70°C	80°C	85°C
Hold Current (A)											
1210 Size											
microSMD005F	0.08	0.07	0.06	0.05	0.05	0.04	0.04	0.03	0.03	0.02	0.02
microSMD010F	0.15	0.13	0.12	0.10	0.10	0.09	0.08	0.06	0.06	0.05	0.05
microSMD035F	0.51	0.46	0.40	0.35	0.34	0.30	0.27	0.24	0.22	0.19	0.18
microSMD050F	0.76	0.66	0.58	0.50	0.48	0.42	0.38	0.35	0.29	0.25	0.23
microSMD075F	1.10	0.97	0.86	0.75	0.72	0.64	0.58	0.55	0.47	0.42	0.39
microSMD110F	1.60	1.42	1.26	1.10	1.06	0.94	0.86	0.80	0.70	0.62	0.58
microSMD150F	2.30	2.02	1.76	1.50	1.43	1.24	1.11	1.00	0.85	0.72	0.65
microSMD175F	2.80	2.45	2.10	1.75	1.70	1.55	1.45	1.35	1.25	1.15	1.10
microSMD200F	2.60	2.44	2.35	2.00	1.96	1.78	1.67	1.50	1.45	1.15	1.10

Temperature Derating Curve



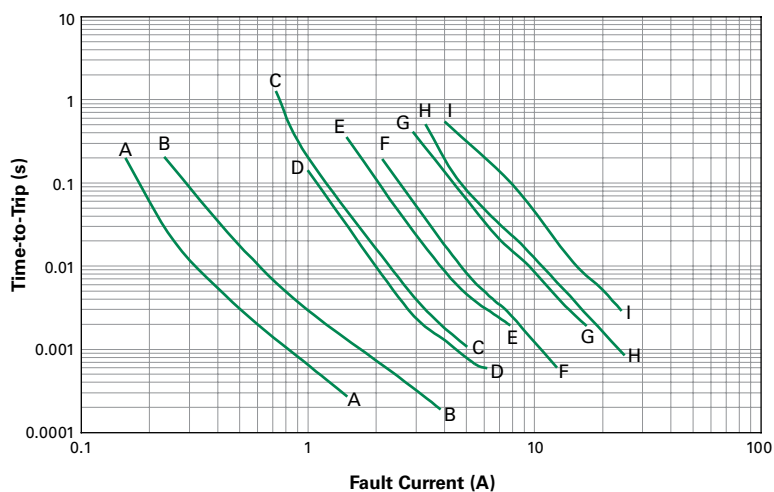
microSMD Series

Surface Mount

Typical Time-to-Trip Curves at 20°C

1210 Series

- A = microSMD005F
- B = microSMD010F
- C = microSMD035F
- D = microSMD050F
- E = microSMD075F
- F = microSMD110F
- G = microSMD150F
- H = microSMD175F
- I = microSMD200F



Note: The average time current curves and Temperature Derating curve performance is affected by a number of variables, and these curves provided as guidance only. Customer must verify the performance in their application.

Physical Specifications

Terminal Pad Material	100% Matte Tin with Nickel Underplate
Soldering Characteristics	ANSI/J-STD-002 Category 3
Solder Heat Withstand	per IEC-STD 68-2-20, Test Tb, Section 5, Method 1a
Flammability Resistance	per IEC 695-2-2 Needle Flame Test for 20 seconds

Environmental Specifications

Test	Test Method	Conditions	Resistance Change
Storage Life	PS300, Section 5.3.2	60°C, 1000 hrs	±3% typ
		85°C, 1000 hrs	±3% typ
Humidity Aging	PS300, Section 5.3.1	85°C, 85% R.H., 100 hrs	±1.2% typ
Thermal Shock	MIL-STD-202, Method 107G	85°C, -40°C (20 Times)	-33% typ
		125°C, -55°C (10 Times)	-33% typ
Vibration	MIL-STD-883C	per MIL-STD-883C	No Change
Solvent Resistance	PS300, Section 5.2.2	Freon	No Change
		Trichloroethane	No Change
		Hydrocarbons	No Change

Moisture Resistance Level	Level 2a, J-STD-020
Storage Conditions	40°C max, 70% RH max; devices should remain in original sealed bags prior to use. Devices may not meet specified values if these storage conditions are exceeded.

microSMD Series

Surface Mount

Dimension Figures

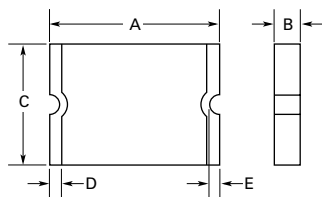


Figure 1

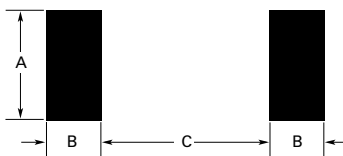
Dimensions

Part Number	Dimensions in Millimeters (Inches)										Figure
	A		B		C		D		E		
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
1210 Size											
microSMD005F	3.0	3.43	0.50	0.85	2.35	2.80	0.25	0.75	0.076	—	1
	(0.118)	(0.135)	(0.019)	(0.034)	(0.092)	(0.110)	(0.010)	(0.030)	(0.003)		
microSMD010F	3.0	3.43	0.50	0.85	2.35	2.80	0.25	0.75	0.076	—	1
	(0.118)	(0.135)	(0.019)	(0.034)	(0.092)	(0.110)	(0.010)	(0.030)	(0.003)		
microSMD035F	3.0	3.43	0.38	0.62	2.35	2.80	0.25	0.75	0.076	—	1
	(0.118)	(0.135)	(0.015)	(0.025)	(0.092)	(0.110)	(0.010)	(0.030)	(0.003)		
microSMD050F	3.0	3.43	0.38	0.62	2.35	2.80	0.25	0.75	0.076	—	1
	(0.118)	(0.135)	(0.015)	(0.025)	(0.092)	(0.110)	(0.010)	(0.030)	(0.003)		
microSMD075F	3.0	3.43	0.38	0.62	2.35	2.80	0.25	0.75	0.076	—	1
	(0.118)	(0.135)	(0.015)	(0.025)	(0.092)	(0.110)	(0.010)	(0.030)	(0.003)		
microSMD110F	3.0	3.43	0.28	0.48	2.35	2.80	0.25	0.75	0.076	—	1
	(0.118)	(0.135)	(0.011)	(0.019)	(0.092)	(0.110)	(0.010)	(0.030)	(0.003)		
microSMD150F	3.0	3.43	0.51	1.22	2.35	2.80	0.25	0.75	0.076	—	1
	(0.118)	(0.135)	(0.020)	(0.048)	(0.092)	(0.110)	(0.010)	(0.030)	(0.003)		
microSMD175F	3.0	3.43	0.40	0.76	2.35	2.80	0.25	0.75	0.076	—	1
	(0.118)	(0.135)	(0.016)	(0.030)	(0.092)	(0.110)	(0.010)	(0.030)	(0.003)		
microSMD200F	3.0	3.43	0.79	1.17	2.35	2.80	0.25	0.75	0.076	—	1
	(0.118)	(0.135)	(0.031)	(0.046)	(0.092)	(0.110)	(0.010)	(0.030)	(0.003)		

microSMD Series

Surface Mount

Recommended Pad Layout



Packaging and Marking Information

Part Number	Tape and Reel Quantity	Standard Package	Part Marking	Recommended Pad Layout Figures [mm (in)]			Agency Recognition
				Dimension A (Nom)	Dimension B (Nom)	Dimension C (Nom)	
1210 Size							
microSMD005F	4,000	20,000	05	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
microSMD010F	4,000	20,000	10	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
microSMD035F	4,000	20,000	3	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
microSMD050F	4,000	20,000	50	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
microSMD075F	4,000	20,000	75	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
microSMD110F	4,000	20,000	11	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
microSMD150F	4,000	20,000	15	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
microSMD175F	4,000	20,000	17	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV
microSMD200F	3,000	15,000	20	2.50 (0.098)	1.00 (0.039)	2.00 (0.079)	UL, CSA, TÜV

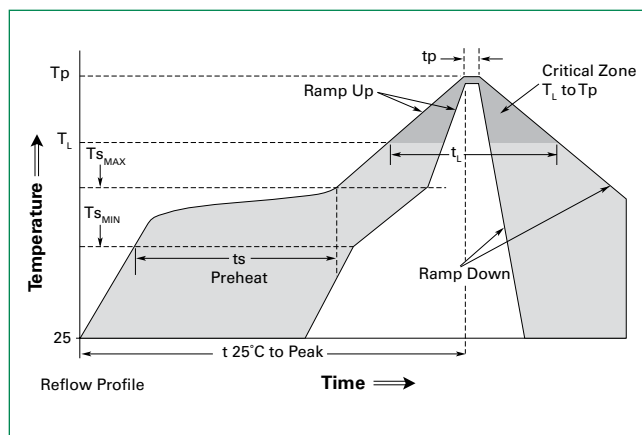
microSMD Series

Surface Mount

Solder Reflow Recommendations

Profile Feature	Pb-Free Assembly
Average ramp up rate (T_{S_MAX} to T_p)	3°C/s max
Preheat	
• Temperature min (T_{S_MIN})	150°C
• Temperature max (T_{S_MAX})	200°C
• Time (t_{S_MIN} to t_{S_MAX})	60-120 s
Time maintained above:	
• Temperature (T_L)	217°C
• Time (t_L)	60-150 s
Peak/Classification temperature (T_p)	260°C
Time within 5°C of actual peak temperature	
Time (t_p)	30 s max
Ramp down rate	3°C/s max
Time 25°C to peak temperature	8 min max

Note: All temperatures refer to topside of the package, measured on the package body surface.



Solder Reflow

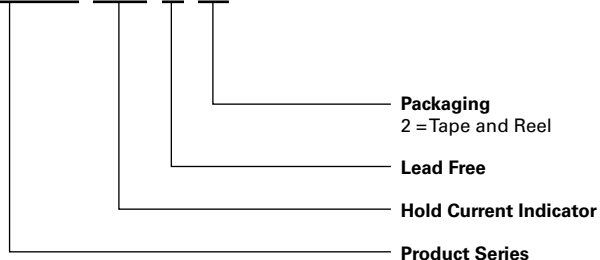
- Recommended reflow method: IR, hot air, nitrogen.
- Recommended maximum paste thickness: 0.25mm (0.010in)
- Devices can be cleaned using standard methods and aqueous solvents.
- Experience has shown the optimum conditions for forming acceptable solder fillets occur when a reasonable amount of solder paste is placed underneath each device's termination. As such, we request that customers comply with our recommended solder pad layouts.
- Customer should validate that the solder paste amount and reflow recommendations meet its application.
- We request that customer board layouts refrain from placing raised features (e.g. vias, nomenclature, traces, etc.) underneath PolySwitch devices. It is possible that raised features could negatively impact solderability performance of our devices.

Rework

- Standard industry practices. (Please also avoid direct contact to the device.)

Part Ordering Number System

microSMD 150 F -2



microSMD Series

Surface Mount

Tape and Reel Specifications

Description	microSMD EIA 481-1 (mm)	
	microSMD005F microSMD010F microSMD035F microSMD050F microSMD075F microSMD110F microSMD150F microSMD175F	microSMD200F
W	8.0 ± 0.30	8.0 ± 0.30
P₀	4.0 ± 0.10	4.0 ± 0.10
P₁	4.0 ± 0.10	4.0 ± 0.10
P₂	2.0 ± 0.05	2.0 ± 0.05
A₀	2.9 ± 0.1	2.9 ± 0.1
B₀	3.5 ± 0.1	3.55 ± 0.1
B₁ max	4.35	4.35
D₀	1.55 ± 0.05	1.55 ± 0.05
F	3.50 ± 0.05	3.50 ± 0.05
E₁	1.75 ± 0.10	1.75 ± 0.10
E₂ min	6.25	6.25
T max	0.3	0.3
T₁ max	0.1	0.1
K₀	0.9 ± 0.1	1.27 ± 0.1
A max	185	185
N min	50	50
W₁	8.4 + 1.5/-0.00	8.4 + 1.5/-0.00
W₂ max	14.4	14.4

microSMD Series

Surface Mount

Tape and Reel Diagrams

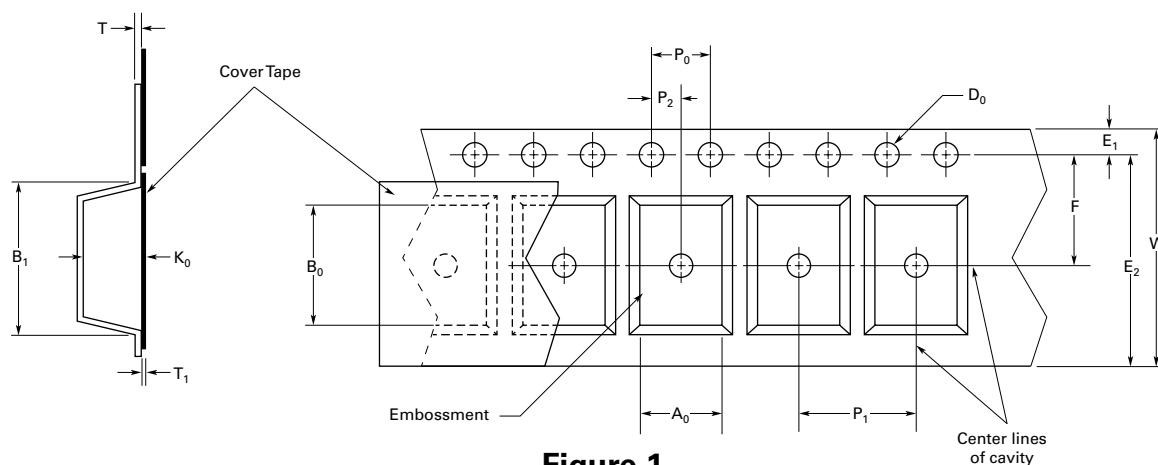


Figure 1

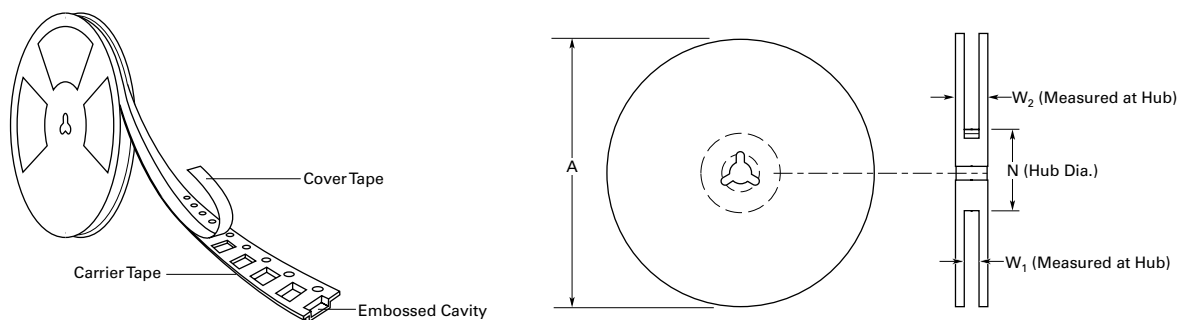


Figure 2

Warning

- Users should independently evaluate the suitability of and test each product selected for their own application.
- Operation beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- These devices are intended for protection against damage caused by occasional overcurrent or overtemperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- Contamination of the PPTC material with certain silicone-based oils or some aggressive solvents can adversely impact the performance of the devices.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- PPTC devices are not recommended for installation in applications where the device is constrained such that its PTC properties are inhibited, for example in rigid potting materials or in rigid housings, which lack adequate clearance to accommodate device expansion.
- Operation in circuits with a large inductance can generate a circuit voltage ($L di/dt$) above the rated voltage of the device.

Disclaimer Notice - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at www.littelfuse.com/disclaimer-electronics.